

Revision History:

E.0: Initial Engineering Release

E.1: P03: Connected Nets on U2 and U3 HDMI ESD protection

P04: Added I2C bus pull-ups on both busses

Changed to 20mil_PAD TP73,TP74,TP75,Tp76,TP68,TP67, TP66, TP64, TP62, TP61, TP60, TP58, TP57,TP54,TP46,TP45,TP44,TP43,TP42,TP41,TP40,TP39,TP38,TP37,TP36,TP35,TP33,TP32,TP31,TP30, TP29, TP22,TP21,TP20,TP19,TP18,TP16,TP15, TP4

Moved Ext_IIC_Bus to pin 3.0 and 3.1 from pin 3.6 and 3.7

Moved MSP430_REQ from pin 7.0 to pin 1.3, IT6801_INTZ from pin 7.6 to pin 1.2, MSP430_ACK from pin 7.4 to pin 1.0, MSP_2IT_RSTN from pin 7.5 to pin 1.1

Removed R3

P05: Removed R50, TPGND4,TPGND6,TPGND9; Changed to 20mil Pad TP82,TP81,TP80,TP79,TP78,TP77

Added pull-down resistor on signal USB_IIC0_OE

P07: Changed to TP 12mil, Drill 32mil Pad TP23, TP14,TP13,TP12,TP11,TP10,TP9,TP8,TP7,TP6,TP5,TP2,TP1

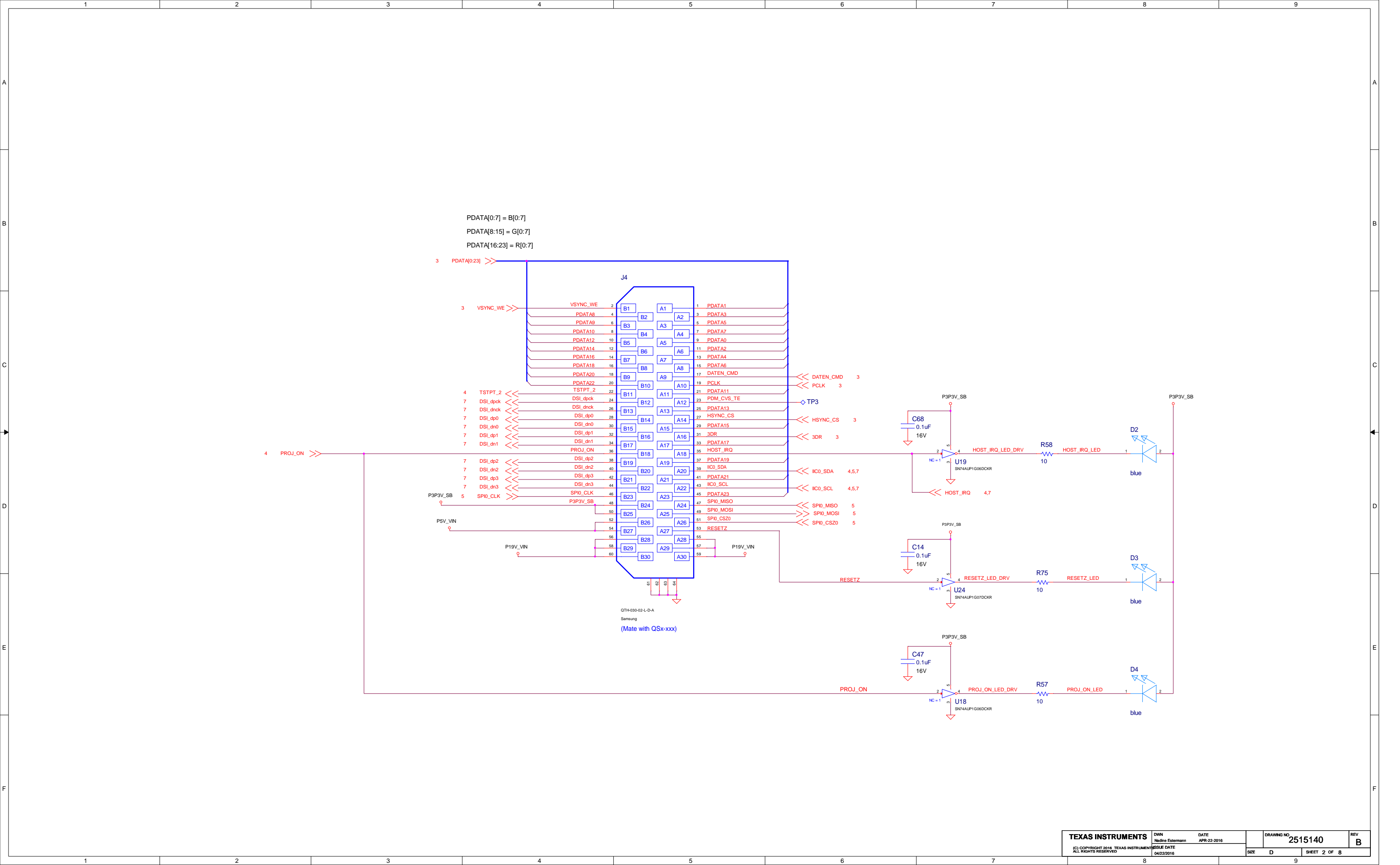
P06: Removed TP28, Added Fuse F1

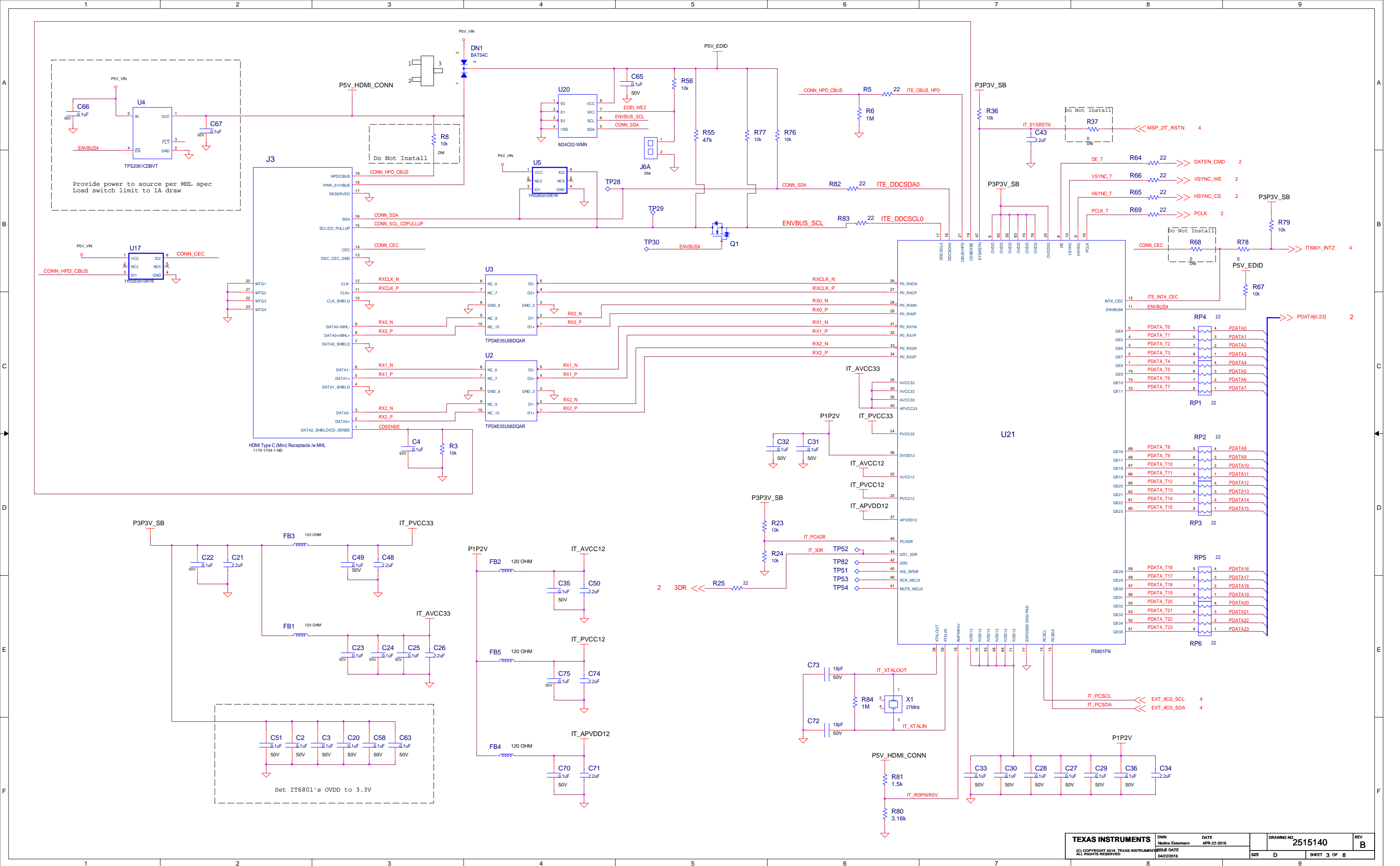
A.0: Official Release - Selected parts which are not needed as DNI

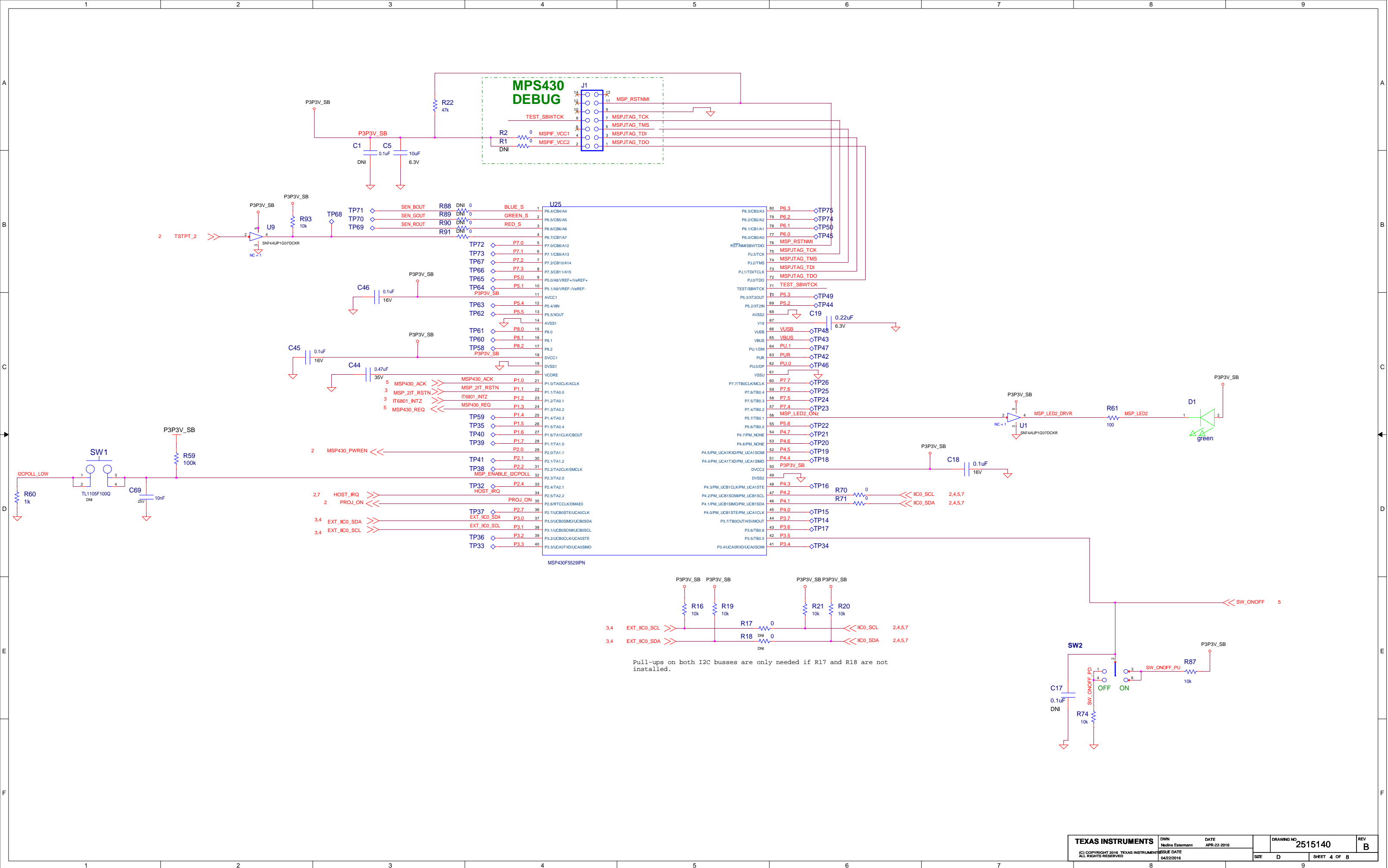
B.0: Changed R8 to DNI and changed version number to match layout

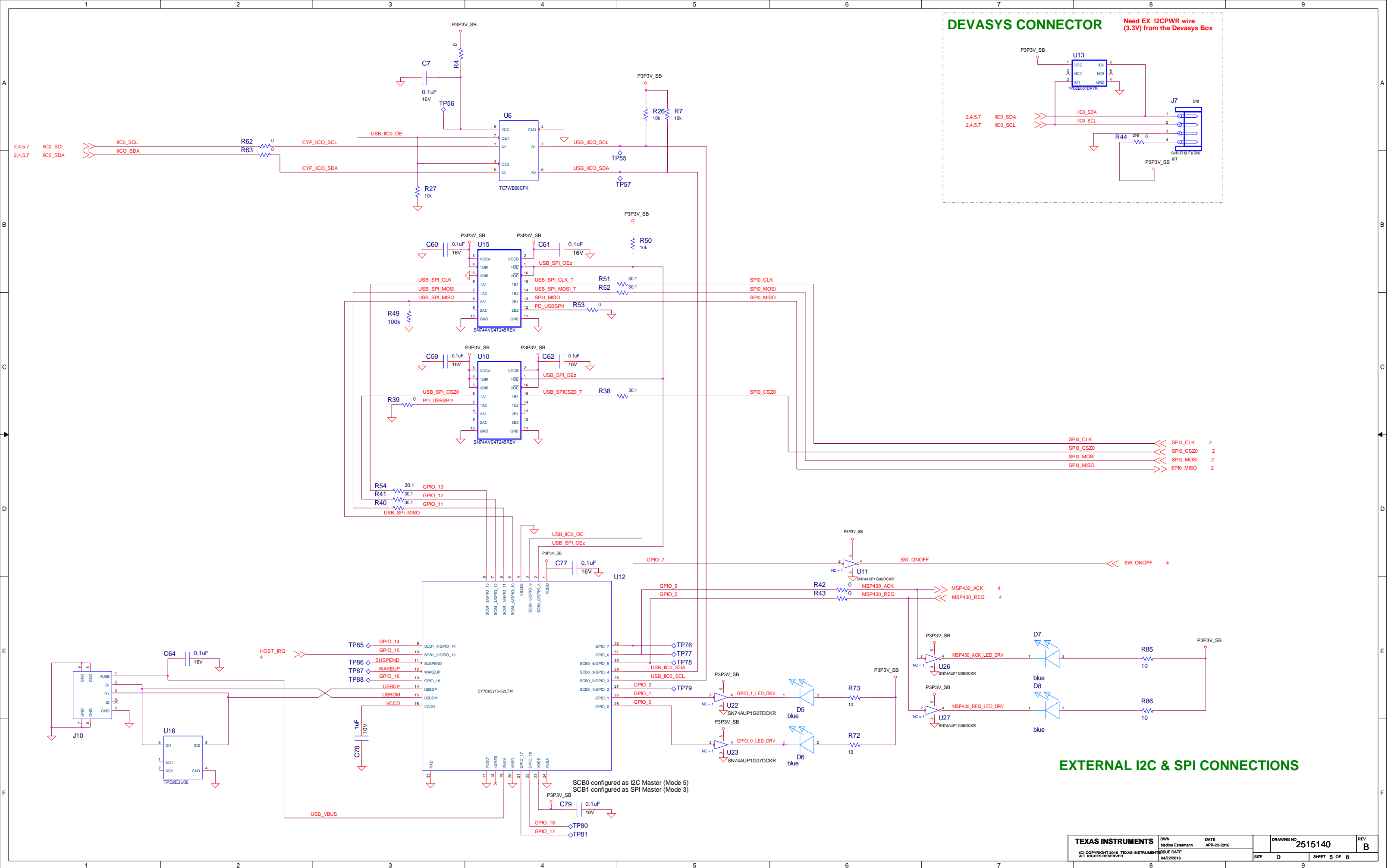
ESD 2515140
PCB 2515141
CCA 2515142

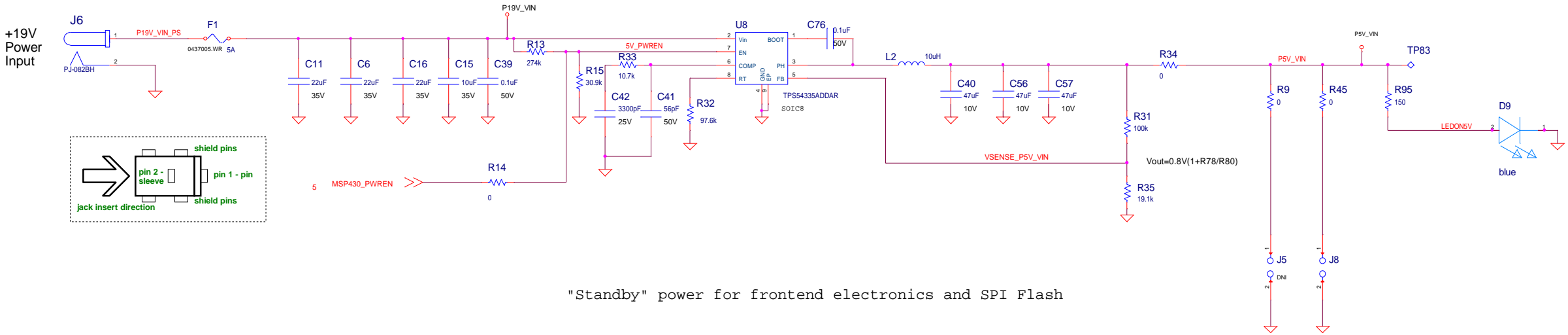
DWN	Nadine Estermann	DATE	APR-22-2016	TEXAS INSTRUMENTS - DLP® Products		
ENGR	Nadine Estermann	APR-22-2016		(C) COPYRIGHT 2016 Texas Instruments Inc. All Rights Reserved		
SYS	Dan Morgan	---		TITLE TIDA-01571 DLP Display LightCrafter 3010 Gen2 Main Board		
APVD	Jeff Dennis	---		DRAWING NO	2515140	REV B
QA	---	---		11 x 17	Orcad Capture 16.6	SHEET 1 of 8



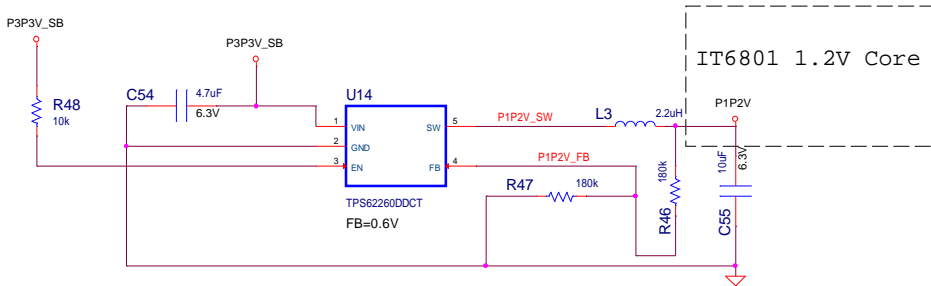
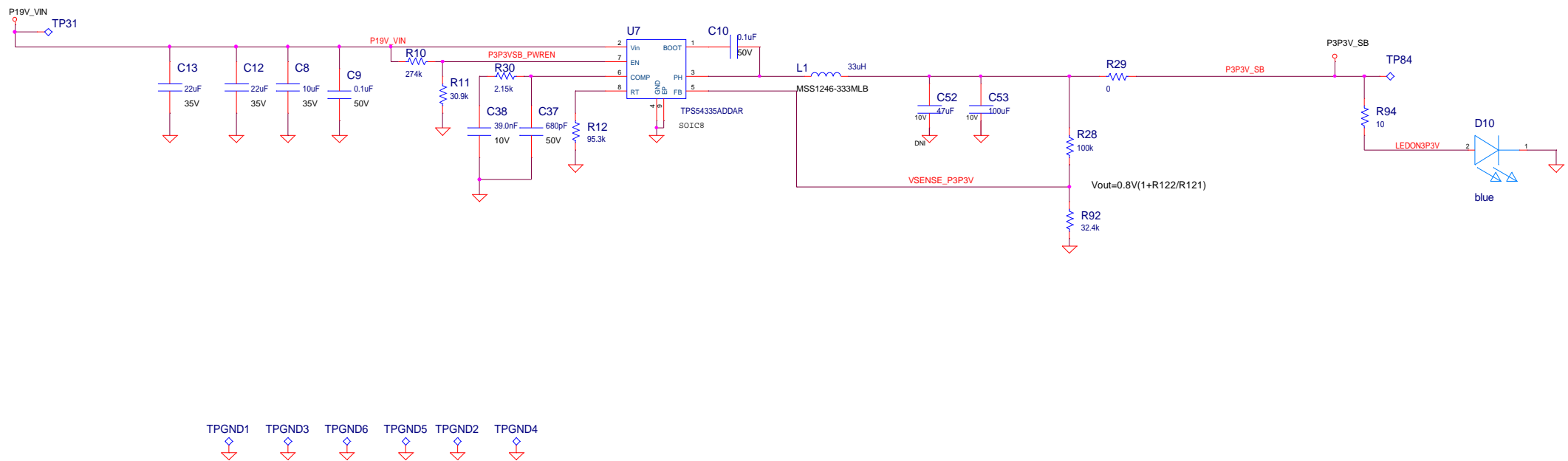


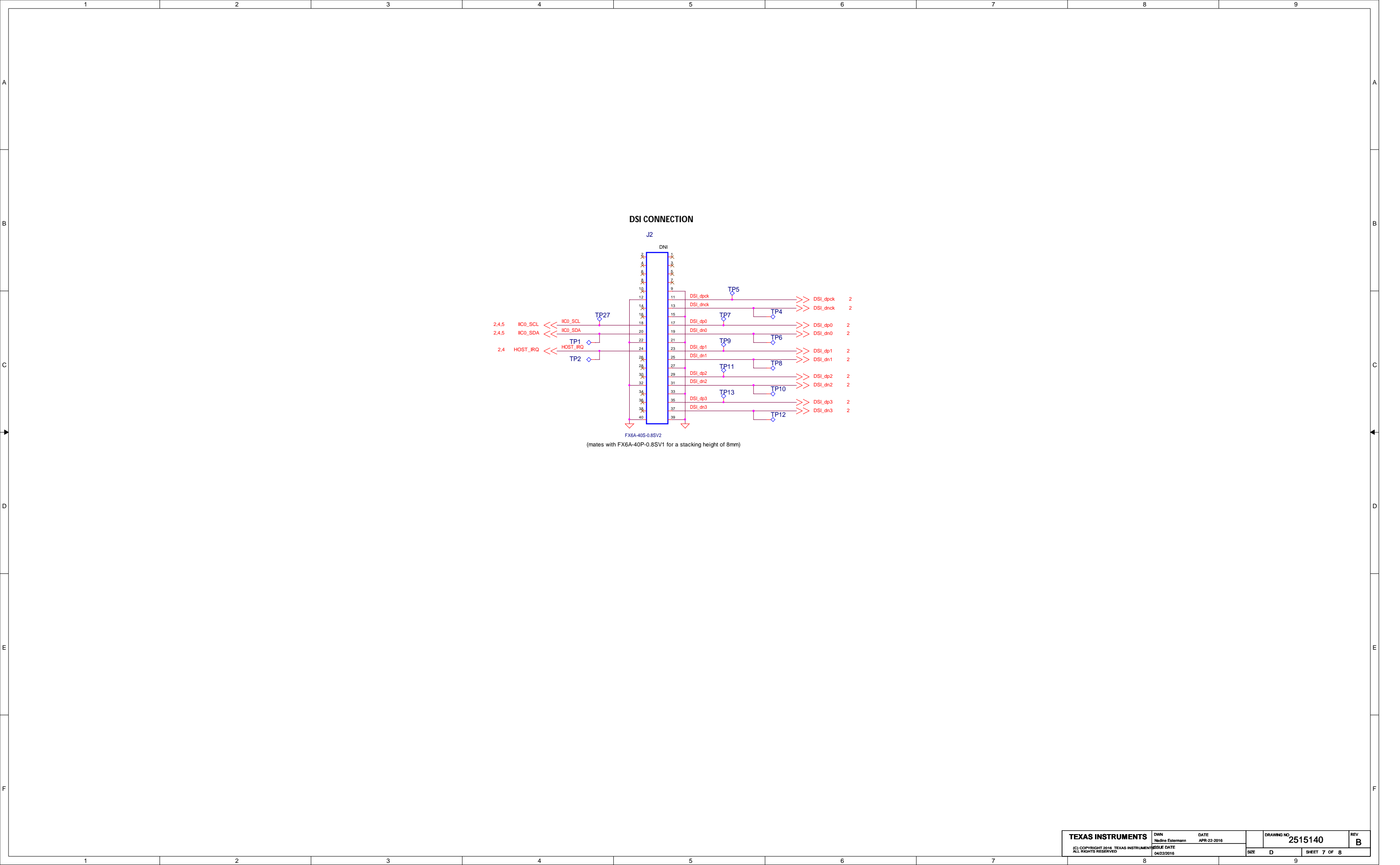






"Standby" power for frontend electronics and SPI Flash





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